

ABSTRACT

The substrate processing apparatus includes a plurality of polishing modules (1A to 1D) arranged in a polishing level for polishing a substrate, a post-processing lane (2A, 2B) arranged in a post-processing level for performing post-processing including cleaning
5 and drying of the polished substrates, and an elevating transporter (5) for removing the polished substrate from one of the plurality of polishing modules (1A to 1D) and directly transporting it to the post-processing lane (2A, 2B). The post-processing level is an upper level located above the polishing level, or a lower level located below the polishing level. The elevating transporter (5) is arranged at the same distance from the plurality of polishing
10 modules (1A to 1D), and has a holding hand (40) that can be elevated and lowered between the polishing level and the post-processing level.

Fig. 1